

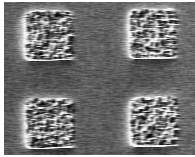
# **TLMI Corporation**

*An employee owned company*

2111 W. Braker Lane, #500  
 Austin, Texas 78758  
 512-833-7075

Strategically located in Central  
 United States.

**TLMI Corporation** provides expertise and quality service for your entire wafer bumping needs. We focus on high quality prototyping, advanced development and lower volume production bumping applications for 3-12" diameter wafers. Additionally, TLMI can help with transferring your device to any high volume wafer bumping company.



## **Indium Bump Technology**

Bump Height Average	Bump Height Uniformity
5-50 $\mu\text{m}$	+/- 5 $\mu\text{m}$ (in Die), +/- 5 $\mu\text{m}$ (in Wafer), +/- 10 $\mu\text{m}$ (Wafer to Wafer)



## **Gold Bump Technology**

Bump Height Average	Bump Height Uniformity
2-30 $\mu\text{m}$	+/- 0.5 $\mu\text{m}$ (in die), +/- 0.5 $\mu\text{m}$ (in Wafer), +/- 1.5 $\mu\text{m}$ (Wafer to Wafer)



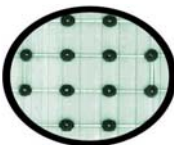
## **Solder Bump Technology**

Bump Height Average	Bump Height Uniformity
25 $\mu\text{m}$ - 250 $\mu\text{m}$	+/- 5 $\mu\text{m}$ (in die), +/- 10 $\mu\text{m}$ (in wafer)



## **Copper Bump Technology**

Bump Height Average	Bump Height Uniformity
10 $\mu\text{m}$ – 100 $\mu\text{m}$	$\pm$ 5 $\mu\text{m}$ (in Die), $\pm$ 15 $\mu\text{m}$ (in Wafer), $\pm$ 20 $\mu\text{m}$ (Wafer to Wafer)



## **Redistribution with Bump Technology**

VIA 1 Minimum Opening	Minimum Trace
30 $\mu\text{m}$	25 $\mu\text{m}$

*Contact us today so we can help you solve your wafer bumping needs.*

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